

CLM, MLE SERIES

(1.00 mm) .0394"

RUGGED RELIABLE MICRO SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLM or www.samtec.com?MLE

Insulator Material:

Black LCP

Contact Material:

CLM: Phosphor Bronze
MLE: BeCu

Plating:

CLM: Au or Sn over 50 μ" (1.27 μm) Ni
MLE: Au over 10 μ" (0.25 μm) Ni

Current Rating (CLM/FTM):

2.8 A per pin

(2 pins powered)

Current Rating (MLE/FTM):

2.9 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Max Cycles:

CLM: 100 with 10 μ" (0.25 μm) Au

Voltage Rating:

MLE: 310 VAC

Insertion Depth:

CLM: Top Entry = (1.40 mm)

.055" min., Bottom Entry = (2.41 mm) .095" min.

(Add board thickness for correct post OAL)

MLE: (1.63 mm) .064" to (3.18 mm) .125" with (0.38 mm) .015" wipe, pass-through, or (2.44 mm) .096" minimum for bottom entry

Normal Force:

CLM: 40 grams (0.39 N) average

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

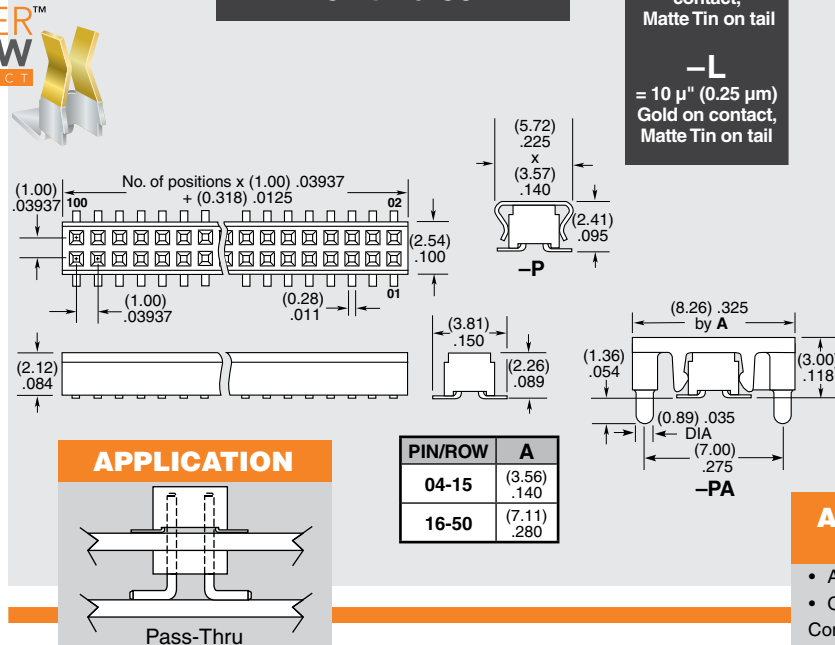
(0.15 mm) .006" max (26-50)

RECOGNITIONS

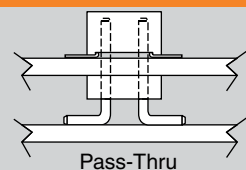
For complete scope of recognitions see www.samtec.com/quality



Mates with:
FTM, FTMH, MW



APPLICATION

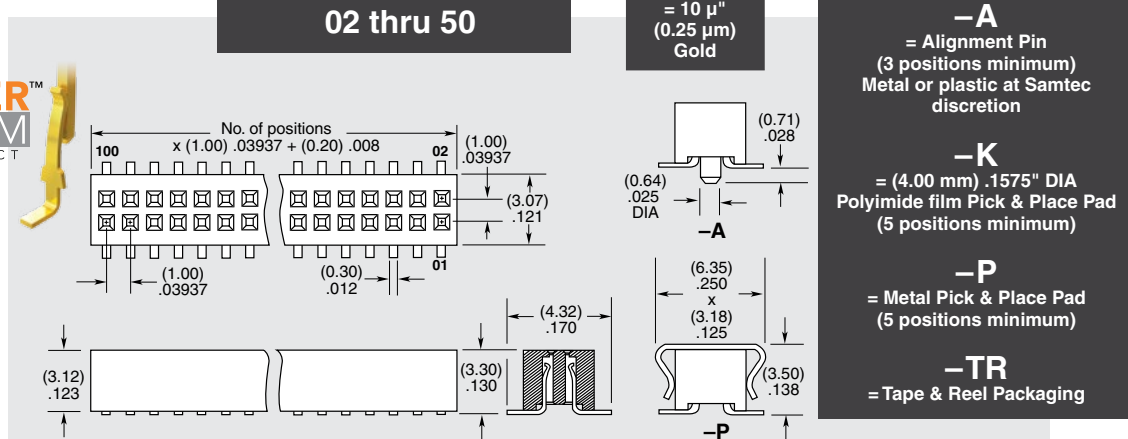


RECOGNITIONS

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Mates with:
FTM, FTMH, MW



Note:
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.